

A1 covered

bottom surface. The integrated circuit package has a lid that is affixed to top of the substrate. The lid is oversized with respect to the substrate so that it has a portion that extends beyond the outer periphery of the substrate. In an aspect of the invention, the periphery of the lid is larger than the outer periphery of the substrate so that the portion of the lid extending beyond the outer periphery of the substrate extends around the outer periphery of the substrate. Supports shims are disposed between the portion of the lid extending beyond the outer periphery of the substrate and portions of a circuit board when the CGA integrated circuit package is mounted on the circuit board. The support shims support the column grid array integrated circuit package against compressive force, such as would be exerted by a cooling solution mounted on the CGA integrated circuit package, and are made of sufficiently rigid material to do so, such as metal or plastic.

Please delete the Abstract Section of the specification and replace it with the following abstract in clean form. Applicant includes herewith an Attachment for Specification Amendments showing a marked up version of the previous version of the Abstract Section.

ABSTRACT OF THE DISCLOSURE

A2

A circuit board assembly has a circuit board and a column grid array ("CGA") integrated circuit package. The CGA integrated circuit package has a substrate having an array of solder columns extending from a bottom surface. An oversized lid is affixed to the substrate. Support shims are disposed between a portion of the lid that extends beyond an outer periphery of the substrate and a circuit board to which the CGA integrated circuit package is mounted. The support shims are affixed to the